

# MECHANICAL CASE OUTLINE

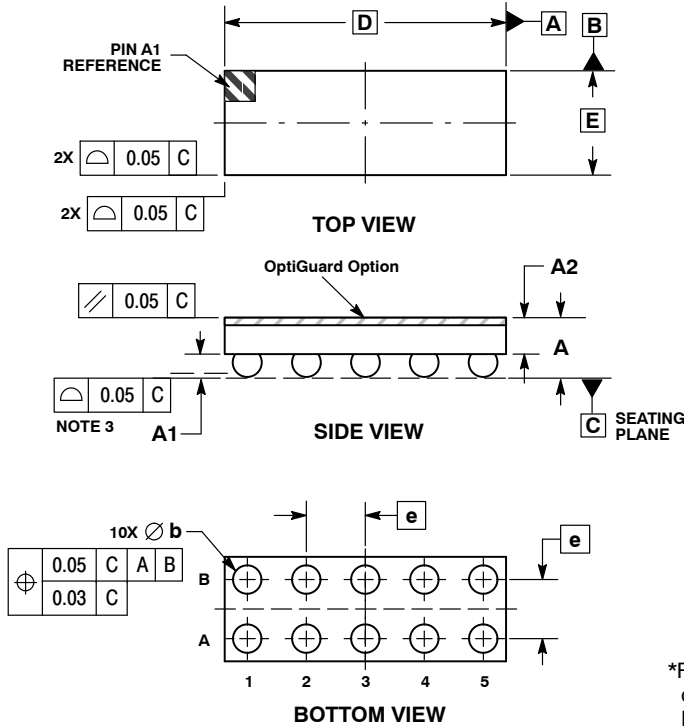
## PACKAGE DIMENSIONS



**WLCSP10, 3.10x1.15**  
CASE 567BM-01  
ISSUE O

SCALE 4:1

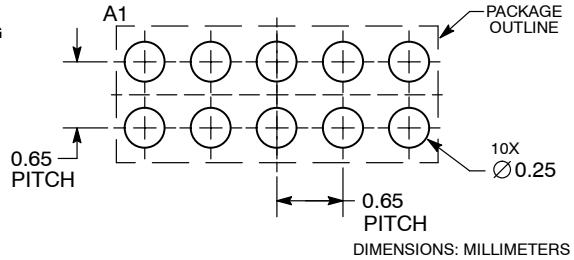
DATE 26 JUL 2010



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.60	0.75
A1	0.23	0.29
A2	0.40 REF	
b	0.34	0.39
D	3.10 BSC	
E	1.15 BSC	
e	0.65 BSC	

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP10, 3.10X1.15</b>	<b>PAGE 1 OF 1</b>

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